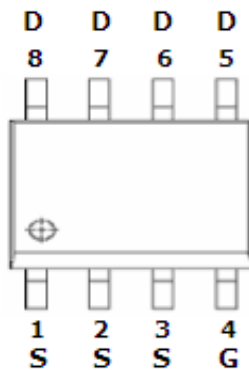


DESCRIPTION

STN4526 is the N-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as power management and other battery powered circuits where high-side switching.

PIN CONFIGURATION SOP-8

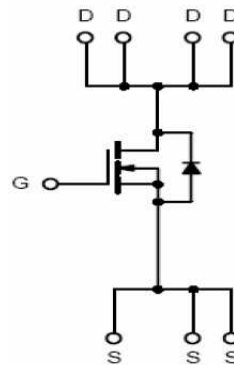


PART MARKING



FEATURE

- 40V/10.0A, $R_{DS(ON)} = 25m\Omega$ (Typ.) @ $V_{GS} = 10V$
- 40V/8.0A, $R_{DS(ON)} = 31m\Omega$ @ $V_{GS} = 4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOP-8 package design



Y: Year Code A: Process Code

ORDERING INFORMATION

Part Number	Package	Part Marking
STN4526	SOP-8P	STN4526

※ Process Code : A ~ Z ; a ~ z

**STN4526**

N Channel Enhancement Mode MOSFET

10.0A

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		VDSS	40	V
Gate-Source Voltage		VGSS	±20	V
Continuous Drain Current (TJ=150°C)	TA=25°C TA=70°C	ID	10.0 8.0	A
Pulsed Drain Current		IDM	30	A
Continuous Source Current (Diode Conduction)		IS	2.3	A
Power Dissipation	TA=25°C TA=70°C	PD	2.5 1.6	W
Operation Junction Temperature		TJ	150	°C
Storage Temperature Range		TSTG	-55/150	°C
Thermal Resistance-Junction to Ambient		RθJA	80	°C/W


STN4526


N Channel Enhancement Mode MOSFET

10.0A

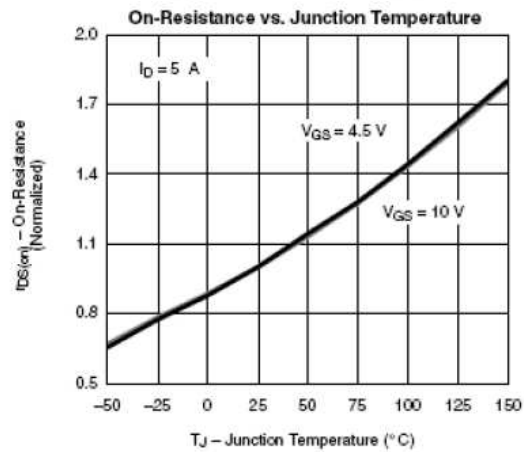
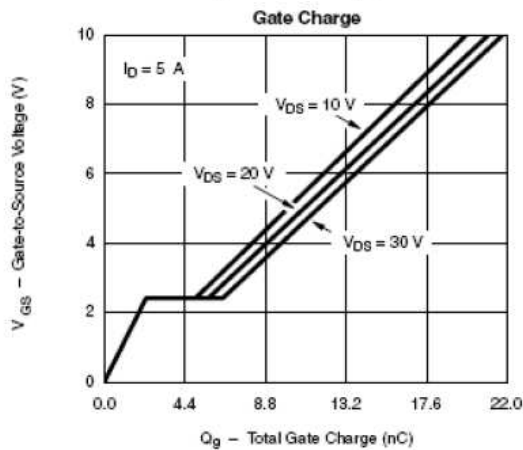
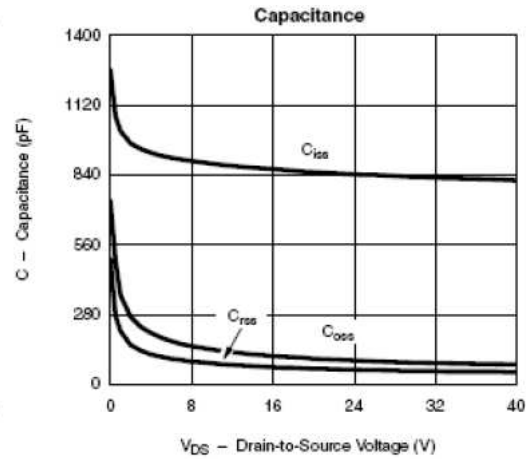
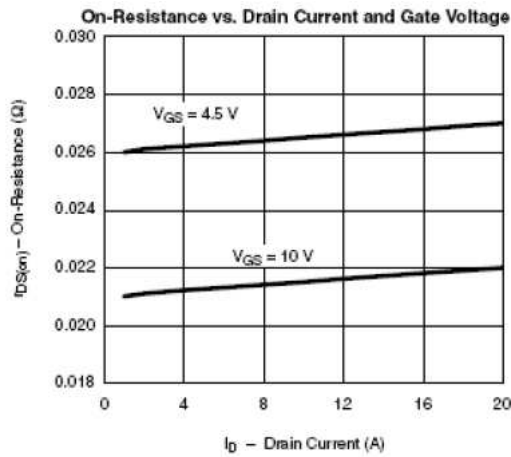
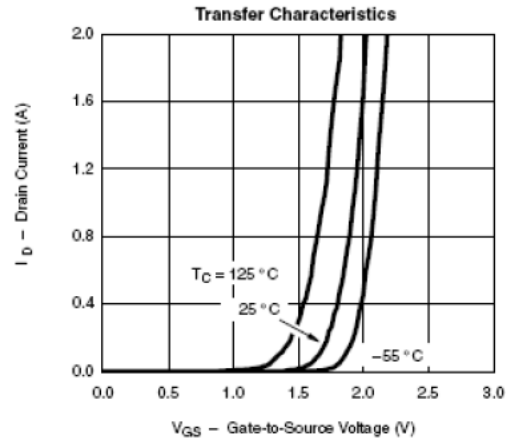
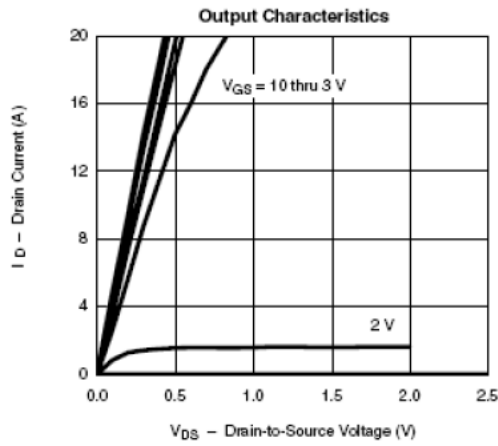
ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

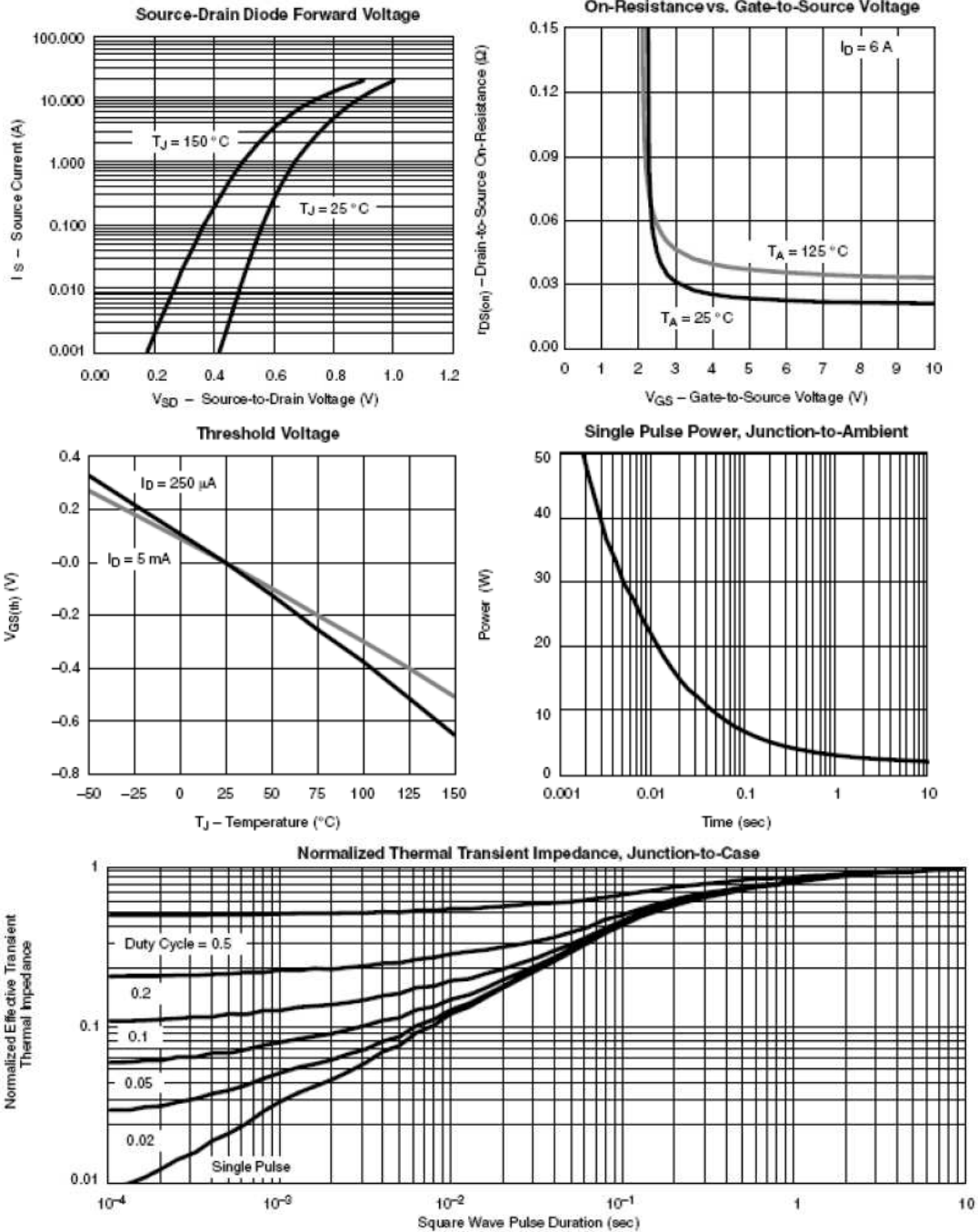
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0		3.0	V
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$			1	μA
		$V_{DS}=40V, V_{GS}=0V$ $T_J=85^{\circ}C$			10	
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$ $V_{GS}=4.5V, I_D=8A$		25 31		mΩ
Forward Transconductance	g_{fs}	$V_{DS}=15V, I_D=6.2A$		13		S
Diode Forward Voltage	V_{SD}	$I_S=2.3A, V_{GS}=0V$		0.8	1.2	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=20V, V_{GS}=4.5V$ $I_D=5A$		10	14	nC
Gate-Source Charge	Q_{gs}			2.8		
Gate-Drain Charge	Q_{gd}			3.2		
Input Capacitance	C_{iss}	$V_{DS}=20V, V_{GS}=0V$ $F=1MHz$		850		pF
Output Capacitance	C_{oss}			110		
Reverse Transfer Capacitance	C_{rss}			75		
Turn-On Time	$t_{d(on)}$ t_r	$V_{DD}=20V, R_L=4\Omega$ $I_D=5.0A, V_{GEN}=10V$ $R_G=1\Omega$		6	12	nS
Turn-Off Time	$t_{d(off)}$ t_f			10	20	
				20	36	
				6	12	

TYPICAL CHARACTERISTICS

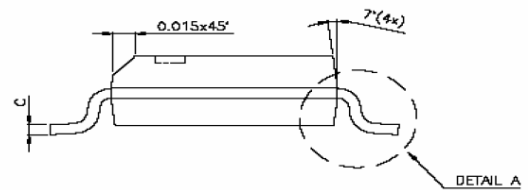
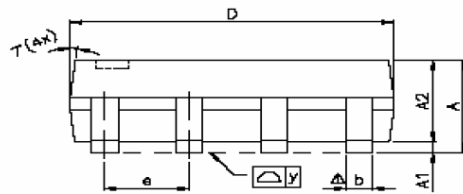
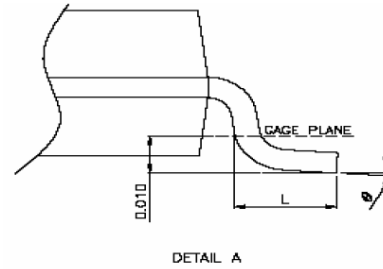
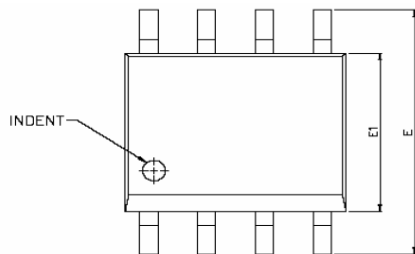
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TYPICAL CHARACTERISTICS


PACKAGE OUTLINE SOP-8P



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	—	0.25	0.004	—	0.010
A2	—	1.45	—	—	0.057	—
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e	—	1.27	—	—	0.050	—
L	0.38	0.71	1.27	0.015	0.028	0.050
Δy	—	—	0.076	—	—	0.003
θ	0°	—	8°	0°	—	8°